

# 晶采光電科技股份有限公司 AMPIRE CO., LTD.

## SPECIFICATIONS FOR LCD MODULE

CUSTOMER	
CUSTOMER PART NO.	
AMPIRE PART NO.	AM-240320DTMQW01H (TFT 3.2")
APPROVED BY	
DATE	

AMPIRE CO., LTD. TOWER A, 4F, No.114, Sec. 1, HSIN-TAI 5th RD., HIS-CHIH, TAIPEI HSIEN, TAIWAN(R.O.C.)

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APPROVED BY	CHECKED BY	ORGANIZED BY

## RECORD OF REVISION

<b>Revision Date</b>	Contents	Editor
2006/3/17	New release	Patrick
2006/3/29	Add the 9H description	Patrick

#### 1 Features

This single-display module is suitable for hand-held application. The LCD adopts one backlight with High brightness 6-lamps white LED.

- (1) LCD: 1.1 Amorphous-TFT 3.2 inch display, transmissive, Normally white type.
  - 1.2 240(RGB)X320 dots Matrix
  - 1.3 LCD Driver IC: Source: Isron IS2102, Gate: Isron IS2202
  - 1.4 Full 262,144 colors display.

Back ground: black (Back-Light, Red, Green, Blue dots are off state)

- 1.5 Viewing Direction 9 o'clock
- (2) Low cross talk by frame rate modulation
- (3) Direct data display with display RAM
- (4) Partial display function: You can save power by limiting the display space.
- (5) RGB or MPU interface selectable.
- (6) Abundant command functions:

Area scroll function

Display direction switching function

Power saving function

(7) Built-in LED driver

Date: 2006/3/29

#### (8) Mechanical specifications

Dimensions and weight

	Item	Specifications	Unit
Active Display Size		3.2 inch diagonal(81.28mm)	mm
	Outline Dimension	55.64 (H) x 77.3(V)	mm
Main LCD	Pixel pitch	0.2025 (H) x 0.2025(V)	mm
	Active area	48.6 (H) x 64.8 (V)	mm
	Number of Pixels	240(H)x320(V) pixels	mm

## 2 Absolute max. ratings and environment

#### 2-1 Absolute max. ratings

Ta=25°C GND=0V

Item	Symbol	Symbol Min.		Unit	Remarks
Power voltage	VDD – GND	-0.3	+4.0	V	
Power voltage	VBAT	-0.5	+6	V	
Input voltage	VIN	-0.5	VDD+0.5	V	

#### 2-2 Environment

Date: 2006/3/29

Item	Specifications	Remarks
Storage temperature	Max. +70 °C Min20 °C	Note 1: Non-condensing
Operating temperature	Max. +60 °C Min10 °C	Note 1: Non-condensing

Note 1 : Ta ≤ +40 °C · · · Max.85%RH

Ta>+40 °C · · · The max. humidity should not exceed the humidity with 40 °C 85%RH.

## 3 Electrical specifications

## 3-1 Electrical characteristics of LCM

 $(V_{DD}=3.0V, Ta=25 \,{}^{\circ}C)$ 

Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
IC power voltage	$V_{DD}$		2.5	3.0	3.3	V
High-level input voltage	V <sub>IHC</sub>		0.8V <sub>DD</sub>		$V_{DD}$	V
Low-level input voltage	V <sub>ILC</sub>		0		0.2V <sub>DD</sub>	V
Consumption current of VDD	I <sub>DD</sub>	LED OFF	-	(6)		mA
Consumption current of LED	I <sub>VBAT</sub>	VBAT=3.0V	-	(180)		mA

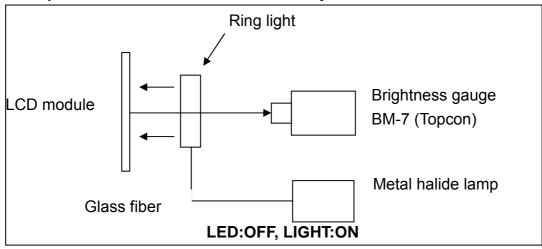
## 3-2 LED back light specification

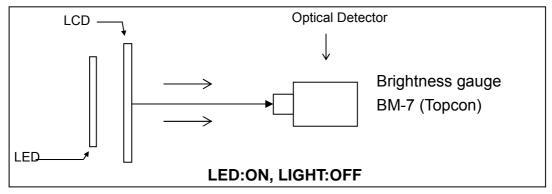
Item	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Forward voltage	$V_{f}$	I <sub>f</sub> =15mA	-	(19)	-	٧
Forward current	I <sub>f</sub>	Vf=19V	-	(15)	(20)	mA
Uniformity (with L/G)	-	I <sub>f</sub> =15mA	70%	-	-	
C.I.E.	Х		0.265	0.30	0.335	
U.I.E.	Y		0.275	0.31	0.345	
Luminous color	White					
Chip connection		6 chip serial connection				

## 4 Optical characteristics

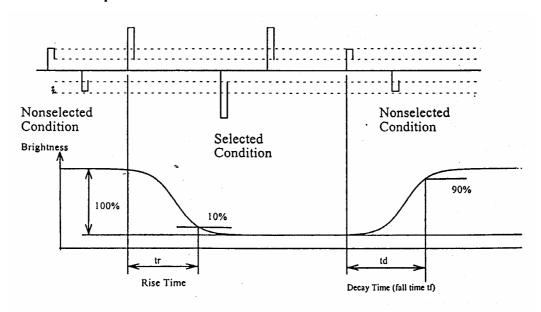
Item		Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Contrast		CR			290			
Basnansa tima	Rising	TR			TBD			
Response time	Falling	T <sub>F</sub>			100		msec	
White luminance (center of scree		YL			160		cd/m <sup>2</sup>	
	Bod	Rx	⊖=0°		0.619			
	Red	Ry	∳=0° Normal viewing angle		0.362			
	Green	Gx			0.326			
Color		Gy			0.580			
chromaticity (CIE1931)	Blue	Bx			0.145			
		Ву			0.076			
	White	Wx			0.310			
		Wy			0.328			
	Hor.	θL			62.2			
Viewing angle	Hoi.	ΘR	CR>10		62.7			
viewing angle	Ver.	Өн			38.7			
	vei.	θL			59.2			

NOTE 1: Optical characteristic measurement system

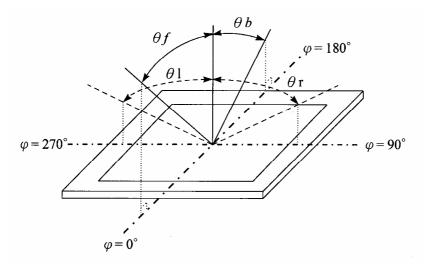




**NOTE 2: Response tome definition** 

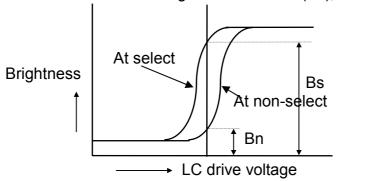


NOTE 3:  $\varphi \cdot \theta$  definition

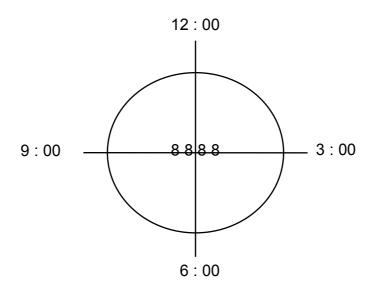


**NOTE 4: Contrast definition** 

CR = Brightness in select (Bs) / Brightness in non-select (Bns)



**NOTE 5: Visual angle direction priority** 



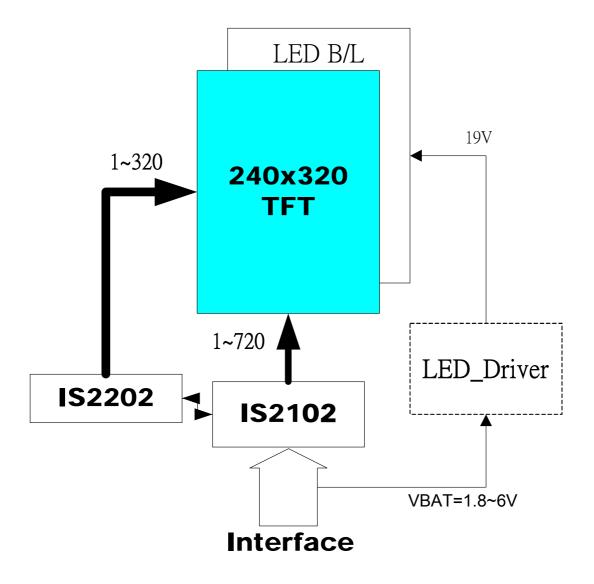
## 5 Block Diagram

Display format: A-Si TFT transmissive, Normally white type.

Display composition: 240(RGB) x 320 dots

LCD Driver: Source: Isron IS2102, Gate: Isron IS2202

Back light: White LED x 6 (I<sub>LED</sub>=15mA)



## 6 Interface specifications

Pin No.	Terminal	Functions
1	VBAT	LED Driver Input 1.8~6V
2	BL-EN	BACKLIGHT ENABLE
3	NC	No Connection
4	VCC	I/O power supply for the system interface (System I/F)
5	VSS	Ground pins
6	ADJ	A pin for external variable resistor to adjust VCOM1 center voltage
7	Dotclk	Dot clock for the RGB interface circuit
		Connect to VCC1A for VSS when not in use
8	Hsync	Horizontal synchronization signal
		Connect to VCC1A or VSS when not in use
9	Vsync	Vertical synchronization signal
		Connect to VCC1A or VSS when not in use
10	RGB/CPU	When IF_SHARE is"H",data pins (D17-D0)
		"L": Used for the System interface circuit
		"H":Used for the RGB interface circuit
11	/RD(E)	i80 series:Read enable signal
		M68 series:"L" Read/Write disable
		"H" Read/Write enable
12	/WR(R/W)	i80 MPU series:Write enable signal
		M68 series "L" Write (same for parallel
		"H" Read and serial interfaces)
13	RS	Selects data or command when transferring parallel/serial data.
		"L" : Command
		"H" : Display data
14	/RESET	Switching to "L" initializes internally.
		Must be reset after the power is supplied.
15	/CS	Chip selection pin.
		The "L" level enables inputting commands and reading /writing data.
16-33	D0-D17	18-bit bidirectional bus
		Connect to VSS when the serial interface is selected.
34	IF_SHARE	"L": Uses data pins(D17-0) only for the system interface circuit.
		"H": Uses data pins(D17-0)both for the system interface circuit and
		For RGB interface circuit.
35	BWS2	"L":18 bits "H" : 16 bits
36-37	BWS1/BWS0	System interface selection
38	DTX2	System interface selection
39	DTX1	System interface selection
40	C86	"L" :i80 series MPU
		"H":M68 series MPU

## **System Interface Circuit**

#### \* PSX is fixed to Low in the display

Pin			Interface Circuit				
PSX	IF_SHARE	RGB./CPU	SI, SO, SCLK	D17-0	RG825-00		
L	L	х	-	System interface circuit	RGB interface circuit		
L	н	L	_	System interface circuit / RGB interface circuit (*1)	_		
L	н	Н	-	RGB interface circuit	-		

IS2102 HAS 18/16/8-bit parallel bus interfaces for the i80 series MPU, and 18/16/8-bit Parallel bus interfaces and 9/8-bit serial interfaces for the M68 series MPU. It is possible to select the interface by the setting of external pins.

Interface		Pin				Interface Number of Transferring of		Transferring method	Transferring	
Type	PSX	BWS1	BWS0	DTX2	DTX1	Mode	data in a	of one dot data	method of one-	
1 9920	Fox	DIVOI	Divou	DIAZ	DIXI	(Bus width)	dot	or one out data	command data	
MPU1	١	L	L	X	X	18-bit parallel	18 bits	18-bit collective		
MPU2	ند	н	L	L	н		18 bits	9-bit twice	40 hit collection	
MPU3	L	Н	L	Н	н	16-bit parallel		16-bit collective		
MPU4	L	Н	L	L	L		16 bits	16-bit collective		
MPU5		Н	н	L	н			6-bit 3 times		
MPU6	L	н	н	н	н	8-bit parallel	18 bits	8-bit + 8-bit + 2-bit	8-bit twice	
MPU7	L	Н	Н	Н	L		16 bits	8-bit twice		
MPU8	Н	L	н	х	X	9-bit serial	18 bits	9-bit twice	9-bit twice	
MPU9	Н	н	н	х	×	8-bit serial	16 bits	8-bit twice	8-bit twice	

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#### 7.1 ADJ connection

#### External Adjustment of Vcom Center Voltage

The IS2202 can adjust the VCOM1 center voltage with external resisters. The ADJTP pin is used for this adjustment. The figure below shows an example of this external adjustment connection. The VCOM1 center voltage is adjusted by adjusting internal and external resistances. This function is available only when internal registers R31 and R32 are set as below. With other settings, both VCOM1 center voltage and VCOM1 amplitude vary as VR changes.

R31 = "95"h R32 = "40"h

When not using this external adjustment function (when ADJTP is OPEN), the VCOM1 center voltage can be set by an internal register (R32).

The VCOM1 amplitude can be changed according to the settings of R31and R32.

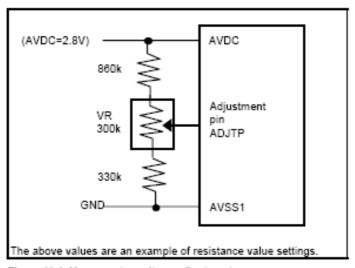
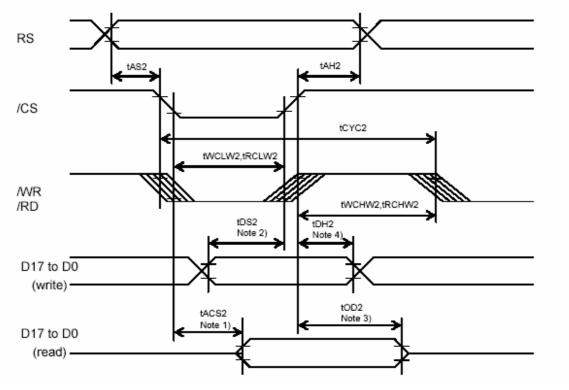


Figure 11-1: Vcom center voltage adjustment

#### 8 AC Characteristics

#### **i80-MPU Connection**



Note 1) . tACS2 is defined by the later timing between "/CS" and "/RD".

Note 2) . tDS2 is defined by the earlier timing between "/CS" and "/RD".

Note 3) . tOD2 is defined by the earlier timing between "/CS" and "/RD".

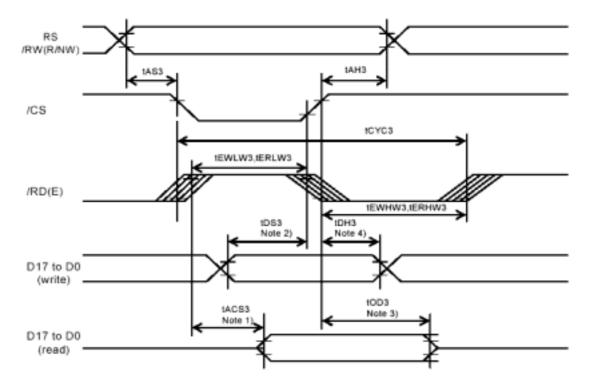
Note 4) . tDH2 is defined by the later timing between "/CS" and "/RD".

(VCC1A=2.8V,VCC1B=2.8V,V18=1.85V,TA=25 degrees C)

Parameter	Symbol	Min.	Max.	Unit
Address set-up time	tAS2	0		ns
Address hold time	tAH2	0		ns
System cycle time (write)	tCYC2	166		ns
System cycle time (read)	tCYC2	350		ns
WR control H pulse width	tWCHW2	70		ns
WR control L pulse width	tWCLW2	70		ns
RD control H pulse width	tRCHW2	60		ns
RD control L pulse width	tRCLW2	130		ns
Data set-up time	tDS2	20		ns
Data hold time	tDH2	0		ns
Access time (CL=100Pf)	tACS2		110	ns
Invalid output time	tOD2	10	100	ns

Please make sure to set "tr" and "tf" to be less than 15ns.

#### **M68-MPU Connection**



Note 1) . tACS3 is defined by the later timing between "/CS" and "E".

Note 2) . tDS3 is defined by the earlier timing between "/CS" and "E".

Note 3) . tOD3 is defined by the earlier timing between "/CS" and "E".

Note 4) . tDH3 is defined by the later timing between "/CS" and "E".

(VCC1A=2.8V,VCC1B=2.8V,V18=1.85V,TA=25 degrees C)

Parameter	Symbol	Min.	Max.	Unit
Address set-up time	tAS3	0		ns
Address hold time	tAH3	0		ns
System cycle time (write)	tCYC3	166		ns
System cycle time (read)	tCYC3	350		ns
Enable H pulse width (write)	tEWHW3	70		ns
Enable L pulse width (write)	tEWLW3	70		ns
Enable H pulse width (read)	tERHW3	60	-	ns
Enable L pulse width (read)	tERLW3	130		ns
Data set-up time	tDS3	20		ns
Data hold time	tDH3	0		ns
Access time (CL=100Pf)	tACS3		110	ns
Invalid output time	tOD3	10	100	ns

Please make sure to set "tr" and "tf" to be less than 15ns.

#### 9. QUALITY AND RELIABILITY

#### 9.1 TEST CONDITIONS

Tests should be conducted under the following conditions:

Ambient temperature :  $25 \pm 5^{\circ}C$ 

Humidity :  $60 \pm 25\%$  RH.

#### 9.2 SAMPLING PLAN

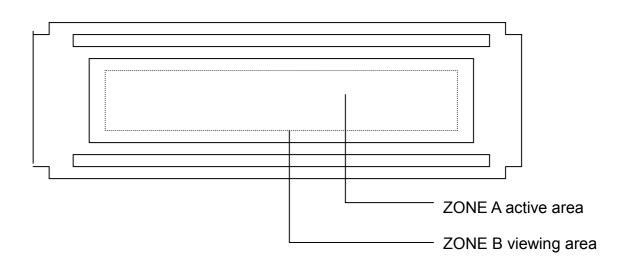
Sampling method shall be in accordance with MIL-STD-105E, level II, normal single sampling plan.

#### 9.3 ACCEPTABLE QUALITY LEVEL

A major defect is defined as one that could cause failure to or materially reduce the usability of the unit for its intended purpose. A minor defect is one that does not materially reduce the usability of the unit for its intended purpose or is an infringement from established standards and has no significant bearing on its effective use or operation.

#### 9.4 APPEARANCE

An appearance test should be conducted by human sight at approximately 30 cm distance from the LCD module under flourescent light. The inspection area of LCD panel shall be within the range of following limits.



## 9.5 INSPECTION QUALITY CRITERIA

No.	Item	Criterion for defects			Defect type		
1	Non display	No non display is allowed			Major		
2	Irregular operation			Major			
		Bright dot Not allowed		Major			
3	Electrical	Dark dot	2		Minor		
	defect	Distance between Dark - dark	I > hmm		Minor		
	Note 1. Bright, Dark dot defect description -bright area is more than 50% of one dot						
	- dark a	rea is more than 50%	of one dot				
4	Mura	ND 8%		Minor			
5	5 Black/White spot (I) Size D (mm)  D ≤ 0.15 0.15 < D ≤ 0.20 0.20 < D ≤ 0.30 0.30 < D		n)	Acceptable number Ignore 3 2 0	Minor		
6	Black/White line (I)	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$		Minor			
7	Black/White sport (II)	Size D (mn D ≤ 0.30 0.30 < D ≤ 0.50 0.50 < D ≤ 1.20 1.20 < D	1)	Acceptable number Ignore 5 3 0	Minor		

8	Black/White line (II)	$ \begin{array}{ c c c c c c } \hline Length \ (mm) & Width \ (mm) & Acceptable \ number \\ \hline 20 < L & 0.05 < W \le 0.07 & 5 \\ 10 < L \le 20 & 0.07 < D \le 0.09 & 3 \\ 5.0 < L \le 10 & 0.09 < D \le 0.10 & 2 \\ L \le 5.0 & 0.10 < D \le 0.15 & 1 \\ \hline \hline 1. \ No \ Lighting \ is \ rejectable \\ \hline                                  $		Minor			
9	Back Light				are reie	ectable	Major
10	Display pattern	2. Flickering and abnormal lighting are rejectable $ \frac{A+B}{2} \leq 0.30  0 < C \qquad \frac{D+E}{2} \leq 0.25  \frac{F+G}{2} \leq 0.25 $ Note: 1. Acceptable up to 3 damages 2. NG if there're to two or more pinholes per dot		Minor			
11	Blemish & Foreign matters  Size: $D = \frac{A+B}{2}$	Size D (r D < 0.15 0.15 < D < 0.20 0.20 < D < 0.30 0.30 < D	te D (mm) Ac ≤ 0.15 ≤ 0.20		Acceptable number Ignore 3 2 0		Minor
12	Scratch on Polarizer	Width (mm)  W≤0.03  0.03 <w≤0.05 0.05<w≤0.08="" 0.08<w="" note(1)="" regard<="" td=""><td colspan="2">L ≤ 2.0 L &gt; 2.0 L &gt; 1.0 L ≤ 1.0 Note (1)</td><td> </td><td>able number gnore gnore 1 1 gnore lote(1)</td><td>Minor</td></w≤0.05>	L ≤ 2.0 L > 2.0 L > 1.0 L ≤ 1.0 Note (1)			able number gnore gnore 1 1 gnore lote(1)	Minor
13	Bubble in polarizer	Size D (mm) Ac $D \le 0.20$ $0.20 < D \le 0.50$ $0.50 < D \le 0.80$ 0.80 < D		Acceptable number Ignore 3 2 0		Minor	
14	Stains on LCD panel surface	Stains that cannot be removed even when wiped lightly with a soft cloth or similar cleaning too are rejectable.			Minor		
15	Rust in Bezel	Rust which is visible in the bezel is rejectable.			Minor		

16	Defect of land surface contact (poor soldering)	Evident crevices which is visible are rejectable.	Minor
17	Parts mounting	Failure to mount parts     Parts not in the specifications are mounted     Polarity, for example, is reversed	Major Major Major
18	Parts alignment	<ol> <li>LSI, IC lead width is more than 50% beyond pad outline.</li> <li>Chip component is off center and more than 50% of the leads is off the pad outline.</li> </ol>	Minor Minor
19	Conductive foreign matter (Solder ball, Solder chips)	<ul> <li>1. 0.45&lt; φ ,N≥1</li> <li>2. 0.30&lt; φ≤0.45 ,N≥1</li> <li>φ:Average diameter of solder ball (unit: mm)</li> <li>3. 0.50<l ,n≥1<="" li=""> <li>L: Average length of solder chip (unit: mm)</li> </l></li></ul>	Major Minor Minor
20	Faulty PCB correction	<ol> <li>Due to PCB copper foil pattern burnout, the pattern is connected, using a jumper wire for repair; 2 or more places are corrected per PCB.</li> <li>Short circuited part is cut, and no resist coating has been performed.</li> </ol>	Minor Minor

#### 9.6 RELIABILITY

Test Item	Test Conditions	Note	
High Temperature Operation	60±3°C , t=96 hrs		
Low Temperature Operation	-10±3°C , t=96 hrs		
High Temperature Storage	70±3°C , t=96 hrs	1,2	
Low Temperature Storage	-20±3°C , t=96 hrs	1,2	
Humidity Test	40°C , Humidity 90%, 96 hrs	1,2	
Thermal Shock Test	-20°C ~ 25°C ~ 70°C 30 min. 5 min. 30 min. (1 cycle ) Total 5 cycle	1,2	
Vibration Test (Packing)	Sweep frequency: 10~55~10 Hz/1min Amplitude: 0.75mm Test direction: X.Y.Z/3 axis Duration: 30min/each axis		

Note 1: Condensation of water is not permitted on the module.

Note 2 : The module should be inspected after 1 hour storage in normal conditions

(15-35°C, 45-65%RH).

#### Definitions of life end point :

- Current drain should be smaller than the specific value.
- Function of the module should be maintained.
- Appearance and display quality should not have degraded noticeably.
- Contrast ratio should be greater than 50% of the initial value.

#### 10 Use precautions

#### 10-1 Handling precautions

- 1) The polarizing plate may break easily so be careful when handling it. Do not touch, press or rub it with a hard-material tool like tweezers.
- 2) Do not touch the polarizing plate surface with bare hands so as not to make it dirty. If the surface or other related part of the polarizing plate is dirty, soak a soft cotton cloth or chamois leather in benzine and wipe off with it. Do not use chemical liquids such as acetone, toluene and isopropyl alcohol. Failure to do so may bring chemical reaction phenomena and deteriorations.
- 3) Remove any spit or water immediately. If it is left for hours, the suffered part may deform or decolorize.
- 4) If the LCD element breaks and any LC stuff leaks, do not suck or lick it. Also if LC stuff is stuck on your skin or clothing, wash thoroughly with soap and water immediately.

#### 10-2 Installing precautions

- 1) The PCB has many ICs that may be damaged easily by static electricity. To prevent breaking by static electricity from the human body and clothing, earth the human body properly using the high resistance and discharge static electricity during the operation. In this case, however, the resistance value should be approx.  $1M\Omega$  and the resistance should be placed near the human body rather than the ground surface. When the indoor space is dry, static electricity may occur easily so be careful. We recommend the indoor space should be kept with humidity of 60% or more. When a soldering iron or other similar tool is used for assembly, be sure to earth it.
- 2) When installing the module and ICs, do not bend or twist them. Failure to do so may crack LC element and cause circuit failure.
- 3) To protect LC element, especially polarizing plate, use a transparent protective plate (e.g., acrylic plate, glass etc) for the product case.
- 4) Do not use an adhesive like a both-side adhesive tape to make LCD surface (polarizing plate) and product case stick together. Failure to do so may cause the polarizing plate to peel off.

#### 10-3 Storage precautions

- 1) Avoid a high temperature and humidity area. Keep the temperature between 0°C and 35°C and also the humidity under 60%.
- 2) Choose the dark spaces where the product is not exposed to direct sunlight or fluorescent light.
- 3) Store the products as they are put in the boxes provided from us or in the same conditions as we recommend.

#### 10-4 Operating precautions

- 1) Do not boost the applied drive voltage abnormally. Failure to do so may break ICs. When applying power voltage, check the electrical features beforehand and be careful. Always turn off the power to the LC module controller before removing or inserting the LC module input connector. If the input connector is removed or inserted while the power is turned on, the LC module internal circuit may break.
- 2) The display response may be late if the operating temperature is under the normal standard, and the display may be out of order if it is above the normal standard. But this is not a failure; this will be restored if it is within the normal standard.
- 3) The LCD contrast varies depending on the visual angle, ambient temperature, power voltage etc. Obtain the optimum contrast by adjusting the LC dive voltage.
- 4) When carrying out the test, do not take the module out of the low-temperature space suddenly. Failure to do so will cause the module condensing, leading to malfunctions.
- 5) Make certain that each signal noise level is within the standard (L level: 0.2Vdd or less and H level: 0.8Vdd or more) even if the module has functioned properly. If it is beyond the standard, the module may often malfunction. In addition, always connect the module when making noise level measurements.
- 6) The CMOS ICs are incorporated in the module and the pull-up and pull-down function is not adopted for the input so avoid putting the input signal open while the power is ON.
- 7) The characteristic of the semiconductor element changes when it is exposed to light emissions, therefore ICs on the LCD may malfunction if they receive light emissions. To prevent these malfunctions, design and assemble ICs so that they are shielded from light emissions.

8) Crosstalk occurs because of characteristics of the LCD. In general, crosstalk occurs when the regularized display is maintained. Also, crosstalk is affected by the LC drive voltage. Design the contents of the display, considering crosstalk.

#### 10-5 Other

- 1) Do not disassemble or take the LC module into pieces. The LC modules once disassembled or taken into pieces are not the guarantee articles.
- 2) The residual image may exist if the same display pattern is shown for hours. This residual image, however, disappears when another display pattern is shown or the drive is interrupted and left for a while. But this is not a problem on reliability.

## 11 Mechanic Drawing

